



Material Content Data Sheet



Sales Product Name	BC 850BW H6327			Issued		29. August 2013		
MA#	MA000854920							
Package	PG-SOT323-3-1			Weight*		5.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		12	
	noble metal	gold	7440-57-5	0.007	0.12		1230	
	inorganic material	silicon	7440-21-3	0.025	0.42	0.54	4203	5446
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		441	
	non noble metal	chromium	7440-47-3	0.008	0.13		1323	
	non noble metal	copper	7440-50-8	2.617	43.91	44.09	439039	440891
wire	non noble metal	copper	7440-50-8	0.008	0.13	0.13	1294	1294
encapsulation	organic material	carbon black	1333-86-4	0.031	0.53		5284	
	plastics	epoxy resin	-	0.677	11.36		113612	
	inorganic material	silicondioxide	60676-86-0	2.441	40.95	52.84	409531	528427
leadfinish	non noble metal	tin	7440-31-5	0.133	2.23	2.23	22263	22263
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1680	1680
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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